

What is claimed is:

1. A semiconductor device in which a bonding pad thereof comprises a first interconnect layer and a second interconnect layer, said bonding pad comprising:

5       a plurality of slit-shaped trenches arranged parallel to each other and formed within an interlayer insulation film provided between said first and second interconnect layers,

          a first connection part provided within one of said  
10 slit-shaped trenches and connecting said first interconnect layer and said second interconnect layer,

          a second connection part and a third connection part provided within other slit-shaped trenches and connecting said first interconnect layer and said second  
15 interconnect layer, respectively, said second connection part and said third connection part being disposed so as to sandwich said first connection part with a prescribed spacing,

          a first bridge connecting part and a second bridge  
20 connecting part, formed in said interlayer insulation film, connecting said first connection part and said second connection part, and

          a third bridge connecting part, formed in said interlayer insulation film, connecting said first  
25 connection part and said third connection part, said third bridge connecting part being disposed between said first bridge connecting part and said second bridge connecting part.

2. A semiconductor device according to claim 1,

wherein a width of a connecting portion of said connection part making connection to said bridge connecting part is narrower than that of said connection part.

5           3. A semiconductor device according to claim 1, wherein a width of a connecting portion of said bridge connecting part making connection to said connection part is narrower than that of said bridge connecting part.

          4. A test method for a semiconductor device in  
10 which a bonding pad thereof comprises a first interconnect layer and a second interconnect layer, said bonding pad comprising;

          a plurality of slit-shaped trenches arranged parallel to each other and formed within an interlayer  
15 insulation film provided between said first and second interconnect layers,

          a first connection part provided within one of said slit-shaped trenches and connecting said first interconnect layer and said second interconnect layer,

20           a second connection part and a third connection part provided within other slit-shaped trenches and connecting said first interconnect layer and said second interconnect layer, respectively, said second connection part and said third connection part being disposed so as  
25 to sandwich said first connection part with a prescribed spacing,

          a first bridge connecting part and a second bridge connecting part, formed in said interlayer insulation film, connecting said first connection part and said

second connection part, and

a third bridge connecting part, formed in said interlayer insulation film, connecting said first connection part and said third connection part, said  
5 third bridge connecting part being disposed between said first bridge connecting part and said second bridge connecting part,

wherein said method comprising;

contacting a test probe for testing said  
10 semiconductor device with said bonding pads so as to be in a direction parallel to a longitudinal direction of said connection part.

5. A test method for a semiconductor device in which a bonding pad thereof comprises a first  
15 interconnect layer and a second interconnect layer, said bonding pad comprising:

a plurality of connection parts, provided within a plurality of slit-shaped trenches formed in an interlayer insulation film, respectively, and connecting said first  
20 interconnect layer and said second interconnect layer, said connection parts being disposed in one direction with a prescribed spacing,

wherein said method comprising;

contacting a test probe for testing said  
25 semiconductor device with said bonding pads so as to be in a direction parallel to a longitudinal direction of said connection part.